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emid. receive, and temporarily retain, a fusible element 321. A reflow operation then fuses solder balls 321 to contacts 305, 307. Any other manner of securing fusible elements 321 to contacts 305, 307 could be used, however.

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**In the Drawings:**

Please amend the drawings in accordance with the redlined version of Figure 1. The amendment to Figure 1, as supported by the present specification, is provided for the purpose of clarity and does not constitute new matter.

**In the Claims:**

Please cancel claims 7, 11, 21-24.

✓ Please add the following claims:

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A4 33. The electrical connector as recited in claim 1, wherein said non-surface mount hold down is adapted to limit flattening of a solder joint between said surface mount contact and the substrate.

34. The electrical connector as recited in claim 1, wherein said non-surface mount hold down is sized with respect to said hole so that said hole does not restrain said surface mount contact from centering on the pad upon mounting to the substrate.

35. The electrical connector as recited in claim 1, wherein said hole is a through hole.

36. The electrical connector as recited in claim 1, wherein said non-surface mount hold down is mounted to the substrate using a reflow process.

37. The ball grid array connector as recited in claim 9, wherein said hold down is adapted to limit flattening of said fusible elements during a reflow process.

38. The electrical connector as recited in claim 25, wherein said distance is selected to limit flattening of said fusible elements during reflow.

39. An electrical connector, mountable to a substrate and comprising  
a housing;  
a surface mount contact secured to said housing and adapted to surface mount to a pad on the substrate; and  
a non-surface mount hold down secured to said housing and adapted to mount to a hole in the substrate so as to allow relative movement between said connector and said substrate during a reflow process.

40. An electrical connector, mountable to a substrate and comprising  
a housing;  
a surface mount contact secured to said housing and adapted to surface mount to a pad on the substrate; and  
a non-surface mount hold down secured to said housing and adapted to

mount to a hole in the substrate, wherein said hole has a perimeter larger than a perimeter of said hold down.

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41. A method of mounting a connector to a substrate, comprising:

- providing an electrical connector having a contact and a hold down;
- providing a substrate having pads and a hole;
- inserting said hold down in said hole, wherein said hole has a perimeter larger than a perimeter than a perimeter of said hold down;
- securing said hold down to said substrate, so as to permit said contacts to center on the pads upon mounting to the substrate; and
- securing said contact to said pads on said substrate.

Please amend the claims to appear as follows:

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1. An electrical connector, mountable to a substrate and comprising:

- a housing;
- a surface mount contact secured to said housing and adapted to surface mount to a pad on the substrate; and
- a non-surface mount hold down secured to said housing and adapted to mount to a hole in the substrate so as to permit said surface mount contact to center on said pad upon mounting to the substrate.

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4. The electrical connector as recited in claim 1, wherein said electrical connector is constructed such that it remains substantially parallel to the substrate when mounted thereon.

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6. The electrical connector as recited in claim 1, wherein said non-surface mount hold down is adapted to retain said housing a distance from a surface of the substrate.

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8. The electrical connector as recited in claim 1, wherein said non-surface mount hold down is a post extending outwardly from said housing.

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9. A ball grid array connector mountable to a substrate, comprising:  
a housing;  
a plurality of contacts within said housing;  
a plurality of fusible elements secured to said contacts for mounting to pads on the substrate; and  
a hold down adapted to enter the substrate so as to permit said fusible elements to center on the pads upon mounting to the substrate, wherein said hold down is secured to said housing.

10. The ball grid array connector as recited in claim 9, wherein said hold down is adapted to retain said housing a distance from a surface of the substrate.

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13. The ball grid array connector as recited in claim 9, wherein said ball grid array connector is constructed such that it remains substantially parallel to the substrate when mounted thereon.

15. A method of mounting an electrical connector to a substrate, comprising:

providing an electrical connector having a contact and a hold down;

providing a substrate having pads;

securing said contact to said pads on said substrate;

placing said hold down into said substrate so as to permit said contacts to center on the pads upon mounting to the substrate; and

securing said hold down to said substrate.

17. The method as recited in claim 15, further comprising constructing said

electrical connector such that it remains substantially parallel to the substrate when mounted thereon.

25. An electrical connector mountable to a substrate, comprising:

a housing having a mounting end facing the substrate;

a plurality of contacts secured to said housing;

a plurality of fusible elements, each secured to a respective one of said plurality of contacts; and

a standoff extending a distance from said mounting end of said housing, and wherein said standoff enters the substrate so as to permit said fusible elements to center on pads upon mounting to the substrate.

31. In a ball grid array connector mountable to a substrate, wherein the

improvement comprises a hold-down adapted to enter an opening in the substrate, so as to permit